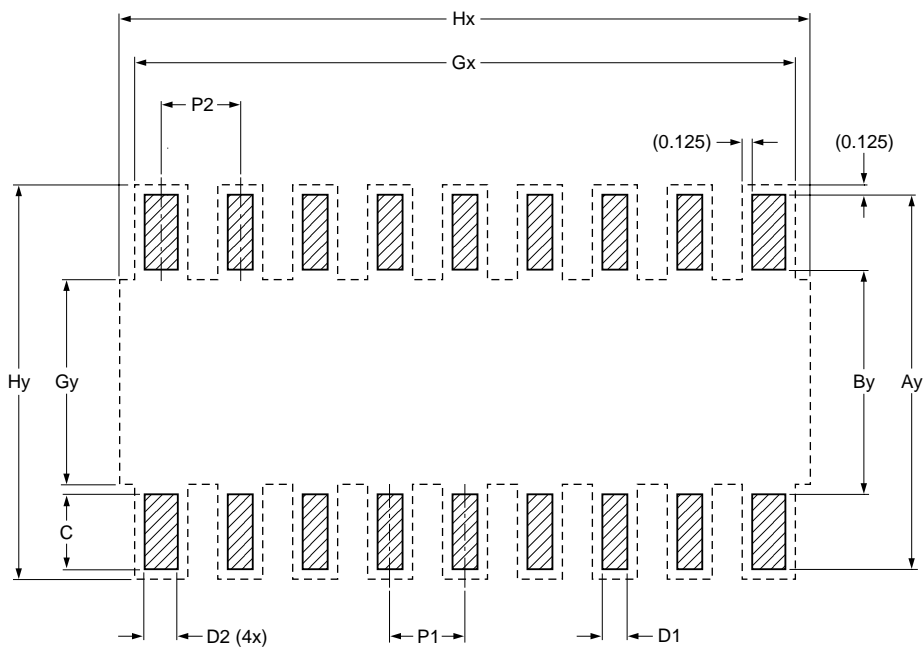



Footprint information for reflow soldering of TSSOP14 package

SOT402-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

 solder land
 - - - - occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.650	0.750	7.200	4.500	1.350	0.400	0.600	4.950	5.300	5.800	7.450